

ATOM130

4-bit Microcontrollers with Reduced 8051 Architecture

CORERIVER Semiconductor reserves the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time.

- ◆ *To discontinue any product or service, CORERIVER should inform customers of that before 3 months through its homepage.*
- ◆ *Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.*
- ◆ *The CORERIVER Semiconductor products listed in this document are intended for usage in general electronics applications. These CORERIVER Semiconductor products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury.*

Copyright CORERIVER Semiconductor Co., Ltd. 2014

All Rights Reserved

1 ATOM130 Overview

1.1 General Description

ATOM130 is a 4-bit reduced 8051 Microcontroller.

ATOM130 has 17 or 13 programmable I/O ports, Watchdog timer, POR (Power-On Reset), built-in I.R. LED Driver, and LVD (Low Voltage Detector) as peripherals.

ATOM130 operates over the extended -20°C to +70°C temperature range, and is available in the 20-pin SOP/TSSOP, 16-pin SOP/TSSOP package.

1.2 Features

- ◆ CPU
 - ✓ 4-bit reduced 8051 architecture
 - ✓ Continuous program addressing, not paged.
 - ✓ 51 instructions including push, pop and logic inst.
 - ✓ Instruction cycle : $F_{SYS}/6$
 - ✓ Multi-level subroutine nesting with RAM based stack.
- ◆ Program Memory (MTP)
 - ✓ 4K Bytes (4,096 X 8 bits)
 - ✓ Multi-programmable by 1K Bytes, 2K Bytes or 4K Bytes
 - ✓ ISP (In System Programming) of MTP
- ◆ Data RAM : 48 nibbles (including stack)
- ◆ I/O Ports
 - ✓ P0 : 4-bit parallel input
 - ✓ P1 : 2-bit parallel input, 2-bit parallel I/O
 - ✓ P2 : 4-bit parallel I/O, Bit-selectable output
 - ✓ P3 : 2-bit parallel I/O, Bit-selectable output
 - ✓ P4 : 3-bit Parallel/bit-selectable Output

- ◆ REM output (Remote control transmitter)
 - ✓ Built-in Transistor for I.R. LED Drive
 - ✓ $I_{OL} = 250 \text{ mA}$ (Max.) at $V_{DD} = 3\text{V}$ and $V_O = 0.3\text{V}$
- ◆ Carrier Pulse Generation : 8 types
- ◆ Built-in Oscillator
 - ✓ Internal Precision Oscillator: 3.64MHz (Typ. $\pm 1\%$)
- ◆ Built-in Reset
 - ✓ Power-on Reset, Power-fail Reset
 - ✓ WDT (Watch-Dog Timer) Reset
 - ✓ Clock switching reset
- ◆ Power Management
 - ✓ Power-down (stop) mode
 - ✓ Release stop by input changes
- ◆ Power Consumption
 - ✓ Stop mode : 1 uA (Max.) at 3.0V
 - ✓ Normal mode : 400 uA (Typ.) at 2.0V, $F_{OSC} = 4 \text{ MHz}$
- ◆ Operating frequency vs. voltage
 - ✓ Max. $F_{SYS} = 4 \text{ MHz}$ ($1.8 \text{ V} \leq V_{DD} \leq 3.6\text{V}$)
- ◆ Operating temperature : -20 °C ~ 70 °C
- ◆ ESD protection
 - ✓ HBM : 2,000V (JESD22-A114E)
 - ✓ MM : 200V (JESD22-A115-A)
 - ✓ CDM : 800V (JESD22-C101-C)
- ◆ Latch-up protection up to $\pm 200\text{mA}$
- ◆ Package
 - ✓ 20-pin TSSOP
 - ✓ 20-pin SOP (JEDEC)
 - ✓ 16-pin TSSOP
 - ✓ 16-pin SOP (Narrow Type)

1.3 Applications

- ◆ Remote Controller

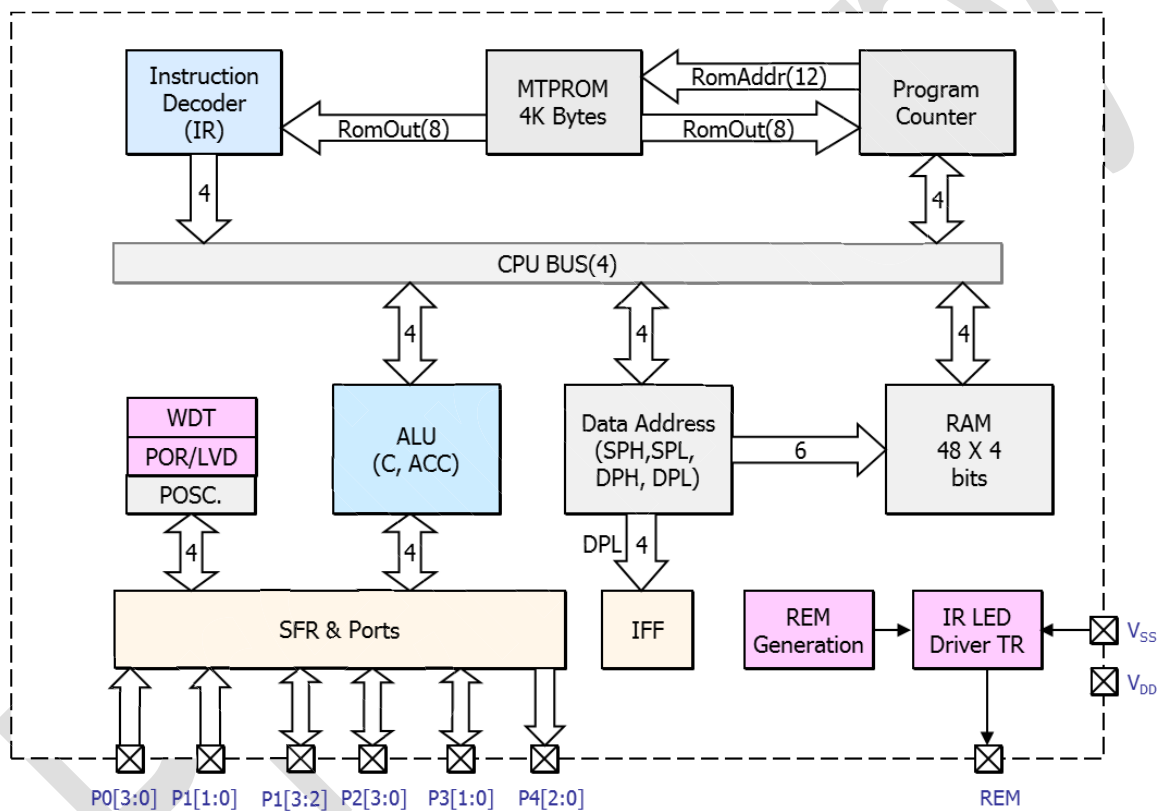
1.4 Product Family Guide

Product	Mask-ROM [Byte]	MTPROM [Byte]	RAM [Nibble]	I/O Pins	Package	Other Peripherals
ATOM130	-	4k	48	17 17 13 13	20-TSSOP 20-SOP 16-TSSOP 16-SOP	WDT ISP LVD POR I.R. LED Driver

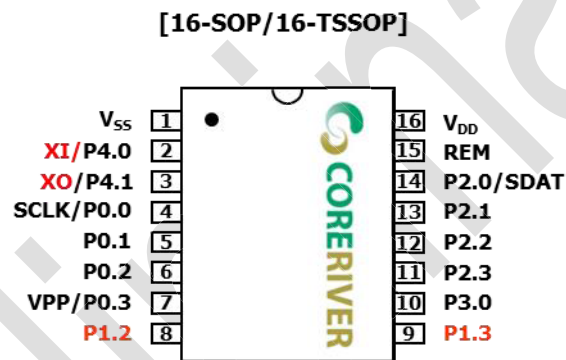
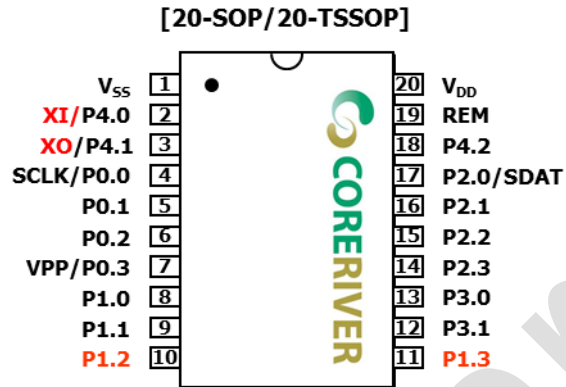
2 Block Diagram

Figure shows the block diagram of **ATOM130**. Programs reside in the internal program memory (Embedded Flash Memory). Data are read from or written to data memory (SRAM) or special function registers (SFRs).

The internal registers of **ATOM130** are configured as part of the on-chip RAM: therefore each register has an address.



3 Pin Configuration



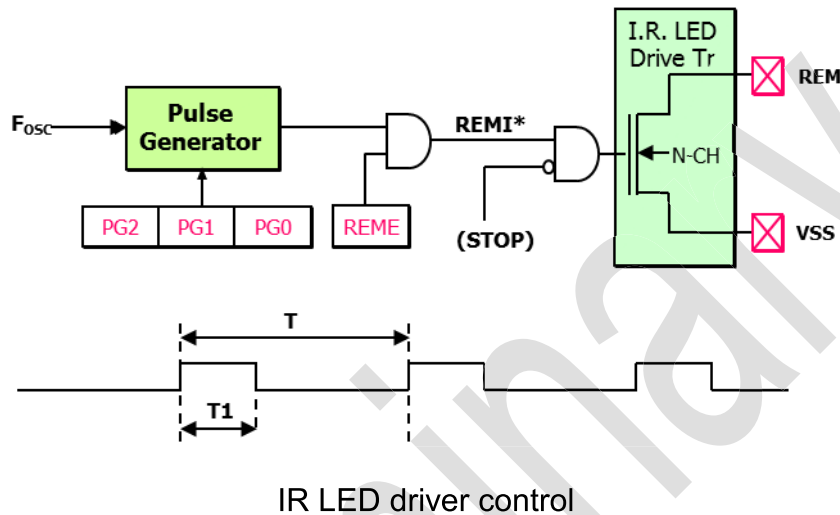
20-pin & 16-pin Package Diagram

4 Pin Description

Symbol	Direction	Description	Remark
V _{DD}	Power	Power Supply	
V _{SS}	Power	Ground	
REM	Output	Output for IR LED drive Transistor. The transistor is n-channel device.	
P4[2:0]	Output	Parallel open-drain Output port. If configured, P4[1:0] is used as XTAL oscillator PADS.	P4.0 : XI P4.1 : XO
P0[3:0]	Input	Parallel Input port with internal pull-up TR. The STOP mode is released by "L" input of each pin. P0[0] and P0[3] are also used for ISP of OTP memory.	P0.0 : SCLK P0.3 : VPP
P1[1:0]	Input	Parallel Input port with internal pull-up TR. The STOP mode is released by "L" input of each pin.	
P1[3:2]	Input/Output	Parallel Input/Output port. Schmitt Trigger input and open-drain output with internal pull-up TR. The STOP mode is released by "L" input of each pin while the port register contains "H".	
P2[3:0]	Input/Output	Parallel Input/Output port. Each bit can be individually set or cleared. Schmitt Trigger input and open-drain output with internal pull-up TR. P2[0] is also used for ISP of OTP memory.	P2.0 : SDAT
P3[1:0]	Input/Output	Parallel Input/Output port. Each bit can be individually set or cleared. Schmitt Trigger input and open-drain output with internal pull-up TR.	

5 Carrier frequency generation

The **ATOM130** family can drive an IR LED for remote controller application. It supports 7 carrier frequencies for data transmission. The REMC register is used for control of the IR LED driver and the carrier frequency.



The IR LED driver is a n-channel MOS transistor. The REM output is the inverse of the REMI* signal. The IR LED is turned on when REMI* is high.

REME	PG2	PG1	PG0	Transmission Control (REMI)	Carrier Frequency ($F_{osc} = 3.64 \text{ MHz}$)
0	X	X	X	0 (Disable)	
1	0	0	0	$1/T = F_{osc}/96$, $T1/T = 1/3$	37.92 KHz
1	0	0	1	$1/T = F_{osc}/64$, $T1/T = 1/2$	56.88 KHz
1	0	1	0	$1/T = F_{osc}/101$, $T1/T = 34/101$	36.04 KHz
1	0	1	1	1 (No carrier)	
1	1	0	0	$1/T = F_{osc}/96$, $T1/T = 1/2$	37.92 KHz
1	1	0	1	$1/T = F_{osc}/65$, $T1/T = 22/65$	56.00 KHz
1	1	1	0	$1/T = F_{osc}/87$, $T1/T = 1/3$	41.84 KHz
1	1	1	1	$1/T = F_{osc}/91$, $T1/T = 31/91$	40.00KHz

Carrier frequency selection

6 Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}	DC supply voltage	-0.3 to 3.6V	V
V_{IN}	DC input voltage	-0.3 to $V_{DD} + 0.3$	V
V_{OUT}	DC output Voltage	-0.3 to $V_{DD} + 0.3$	V
I_{OL}	DC output low current	One I/O pin active: 20	mA
		All I/O pins active: 100	mA
T_{STG}	Storage temperature	-55 to 125	°C
T_{SOL}	Soldering temperature	260 for 10 seconds	°C

7 Recommended Operating Conditions

Symbol	Parameter	Rating	Unit
V_{DD}	DC supply voltage	1.8 to 3.6	V
T_A	Industrial temperature range	-20 to 70	°C

8 DC Characteristics

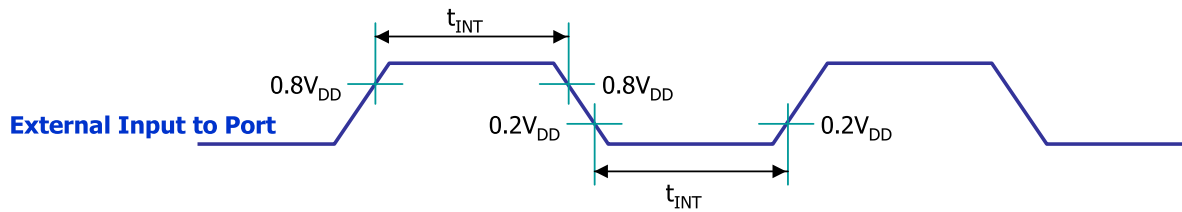
($T_A = -20^{\circ}\text{C} \sim +70^{\circ}\text{C}$, $V_{DD} = 1.8\text{V} \sim 3.6\text{V}$ unless otherwise specified)

Parameter	Symbol	Pin	Conditions	Value			Unit
				Min.	Typ.	Max.	
Input low voltage	V_{IL1}	P0, P1, P2, P3	$V_{DD} = 1.8\text{V} \sim 3.6\text{V}$	-0.3	-	$0.2V_{DD}$	V
Input high voltage	V_{IH1}	P0, P1, P2, P3	$V_{DD} = 1.8\text{V} \sim 3.6\text{V}$	$0.8V_{DD}$	-	$V_{DD} + 0.3$	V
Input high leakage current	I_{IH}	All pins except XI, XO	$V_{IN} = V_{DD}$	-1	-	+1	μA
Output low voltage	V_{OL}	P1, P2, P3, P4	$I_{OL} = 8\text{mA} @ V_{DD} = 3\text{V}$	-	-	$0.3V_{DD}$	V
Output low voltage	V_{OL2}	REM	$I_{OL} = 250\text{mA} @ V_{DD} = 3\text{V}$	-	-	0.4	V
Output high voltage	V_{OHP}	Pull-up current	$I_{OHP} = -50\mu\text{A} @ V_{DD} = 3\text{V}$	$0.7V_{DD}$	-	-	V
Pin capacitance	C_{IO}	All	$V_{DD} = 5\text{V}$	-	10	-	pF

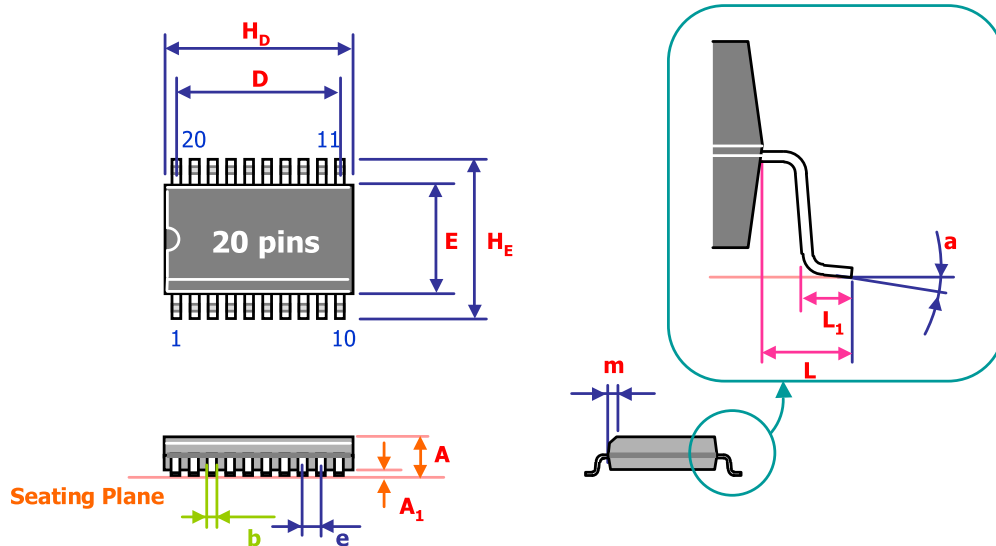
9 AC Characteristics

($T_A = -20^\circ\text{C} \sim +70^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Pin	Conditions	Value			Unit
				Min.	Typ.	Max.	
Operating Frequency (Internal Clock)	F_{OSC}		$1.8\text{V} \leq V_{\text{DD}} \leq 3.6\text{V}$	3.64 -2%	3.64	3.64 +2%	MHz
System Frequency	F_{SYS}		$1.8\text{V} \leq V_{\text{DD}} \leq 3.6\text{V}$	1/8	-	1	F_{OSC}
External Input Width	t_{INT}	P0, P1, P2, P3	$1.8\text{V} \leq V_{\text{DD}} \leq 3.6\text{V}$	12	-	-	F_{SYS}



10 20-pin TSSOP Package Dimension

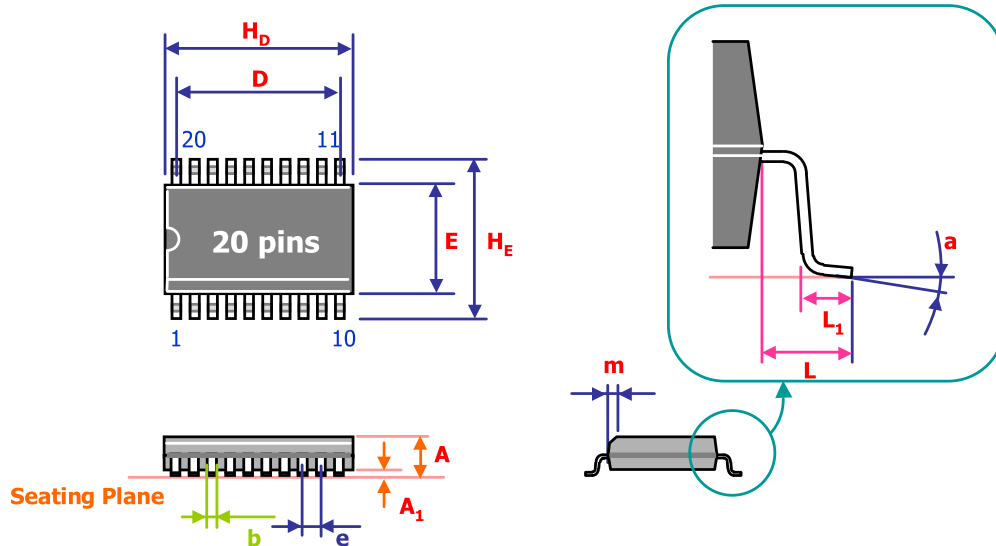


Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A			0.043			1.1
A ₁	0.001		0.006	0.020		0.150
b	0.007		0.012	0.190		0.300
D		0.234			5.850	
E	0.169	0.174	0.177	4.300	4.400	4.500
H _D	0.252	0.254	0.259	6.400	6.500	6.600
H _E	0.246	0.252	0.258	6.250	6.400	6.550
L	0.038	0.039	0.040	0.975	1.000	1.025
L ₁	0.020	0.024	0.028	0.500	0.600	0.700
a	1°	-	7°	1°	-	7°
e	0.026 BSC			0.65 BSC		

Notes:

1. Dimension D & E include mold mismatch and are determined at the mold parting line.
2. General appearance spec. should be based on final visual inspection spec.

11 20-pin SOP Package Dimension

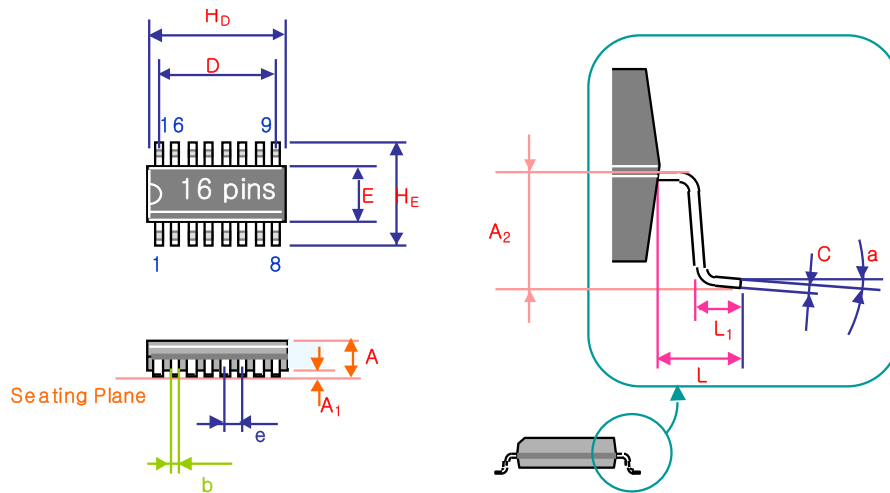


Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	0.106	-	-	2.7
A_1	0.004	-	-	0.1	-	-
b	0.013	0.016	0.020	0.324	0.4	0.51
E	0.264	0.295	0.324	6.71	7.5	8.23
H_D	0.495	0.504	0.512	12.57	12.8	13
H_E	0.394	0.406	0.419	10.0	10.3	10.643
L	0.016	-	0.052	0.406	-	1.32
a	0°	-	8°	0°	-	8°
e	0.050 BSC			1.27 BSC		

Notes:

1. Dimension D & E include mold mismatch and are determined at the mold parting line.
2. General appearance spec. should be based on final visual inspection spec.

12 16-pin TSSOP Package Dimension

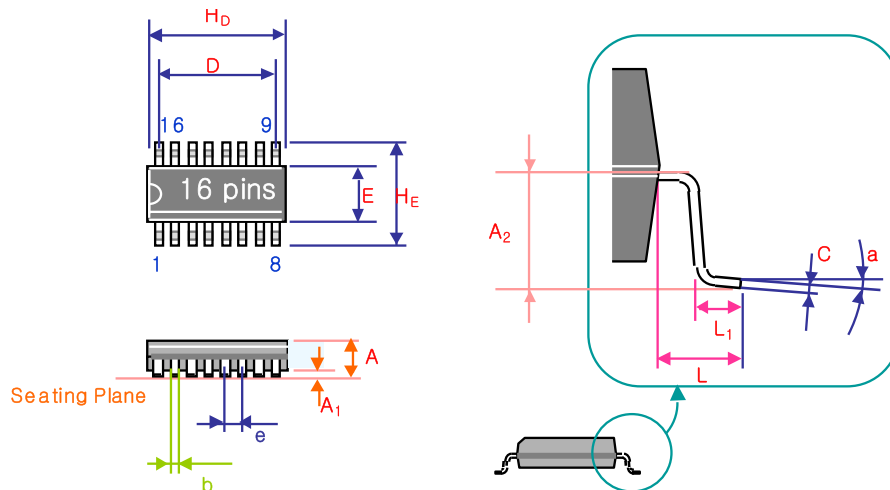


Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.037	0.039	0.041	0.95	1.00	1.05
A ₁	0.015	0.017	0.019	0.3865	0.4365	0.4865
A ₂	0.026	0.028	0.030	0.65	0.7	0.75
b	0.008	0.009	0.009	0.20	0.22	0.24
C	0.004	0.006	0.008	0.09	0.145	0.20
D	0.176	0.179	0.182	4.47	4.55	4.63
E	0.171	0.173	0.175	4.35	4.4	4.45
H _D	0.200	0.202	0.204	5.077	5.127	5.177
H _E	0.248	0.252	0.256	6.30	6.40	6.50
L	0.033	0.037	0.041	0.85	0.95	1.05
L ₁	0.020	0.024	0.028	0.50	0.60	0.70
a	1°	3°	5°	1°	3°	5°
e	0.026 BSC			0.65 BSC		

Notes:

1. Dimension D & E include mold mismatch and are determined at the mold parting line.
2. General appearance spec. should be based on final visual inspection spec.

13 16-pin SOP Package Dimension



Symbol	Dimension in Inches			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.093	0.099	0.104	2.35	2.45	2.65
A ₁	0.004	0.008	0.012	0.10	0.20	0.30
b	0.014	0.016	0.019	0.35	0.42	0.49
D	-	.350	-	-	8.89	-
E	0.150	0.153	0.157	3.80	3.90	4.00
H _D	0.398	0.405	0.413	10.10	10.29	10.50
H _E	0.234	0.239	0.244	5.95	6.07	6.20
L	0.038	0.043	0.048	0.97	1.08	1.2
L ₁	0.022	0.027	0.032	0.58	0.70	0.82
a	0°	-	8°	0°	-	8°
e	0.050 BSC			1.27 BSC		

Notes:

1. Dimension D & E include mold mismatch and are determined at the mold parting line.
2. General appearance spec. should be based on final visual inspection spec.